



A Product Line of Diodes Incorporated

ZXTC2062E6

20V COMPLEMENTARY MEDIUM POWER TRANSISTORS IN SOT26

Features

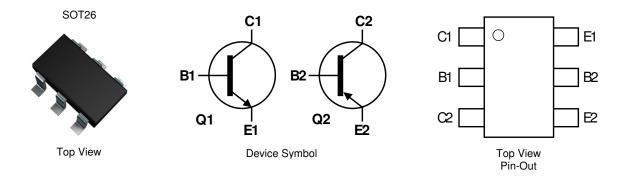
- NPN + PNP Combination
- BV_{CEO} > 20 (-20)V
- BV_{EBO} > 7 (-7)V
- Continuous Collector Current I_C = 4 (-3.5)A
- V_{CE(sat)} < 50 (-65)mV @ 1A
- R_{CE(sat)} = 35 (54)mΩ
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ©3
- Weight: 0.015 grams (Approximate)

Applications

- MOSFET and IGBT Gate Driving
- Motor Drive



Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC2062E6TA	2062	7	8	3,000

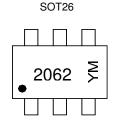
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
 Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

Notes:



 $\begin{array}{l} 2062 = \mbox{Product Type Marking Code} \\ \mbox{YM} = \mbox{Date Code Marking} \\ \mbox{Y or } \overline{Y} = \mbox{Year (ex: C = 2015)} \\ \mbox{M or } \overline{M} = \mbox{Month (ex: 9 = September)} \end{array}$

Date Code	Key													
Year	201	5	201	6	2017	2018	2019	2020	2021	1 20	22 2	2023	2024	2025
Code	С		D		E	F	G	Н			J	К	L	М
Montl	n	Ja	n	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	•	1		2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings – Q1 (NPN Transistor) (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	100	V
Collector-Emitter Voltage	V _{CEO}	20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	5	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	Ι _C	4	A
Peak Pulsed Collector Current	I _{CM}	10	A
Base Current	IB	1	A

Absolute Maximum Ratings – Q2 (PNP Transistor) (@TA = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-25	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	-4	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	lc	-3.5	A
Peak Pulsed Collector Current	I _{CM}	-10	A
Base Current	IB	-1	А

Thermal Characteristics (@TA = +25 °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 5 & 9)		0.7 5.6		
	(Notes 6 & 9)		0.9 7.2		
Power Dissipation Linear Derating Factor	(Notes 6 & 10)	PD	1.1 8.8	W mW/°C	
, i i i i i i i i i i i i i i i i i i i	(Notes 7 & 9)		1.1 8.8		
	(Notes 8 & 9)		1.7 13.6		
	(Notes 5 & 9)		179		
	(Notes 6 & 9)		139		
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	$R_{ extsf{ heta}JA}$	113		
	(Notes 7 & 9)		113	°C/W	
	(Notes 8 & 9)		73		
Thermal Resistance, Junction to Lead	(Note 11)	R _{θJL}	87.5		
Operating and Storage Temperature Range	·	TJ, T _{STG}	-55 to +150	°C	

ESD Ratings (Note 12)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes: 5. For a device surface mounted on 15mm x 15mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

6. Same as Note (5), except the device is surface mounted on 25mm x 25mm 1oz copper.

7. Same as Note (5), except the device is surface mounted on 50mm x 50mm 2oz copper.

8. Same as Note (7), except the device is measured at t < 5 seconds.

9. For device with one active die, both collectors attached to a common heatsink.

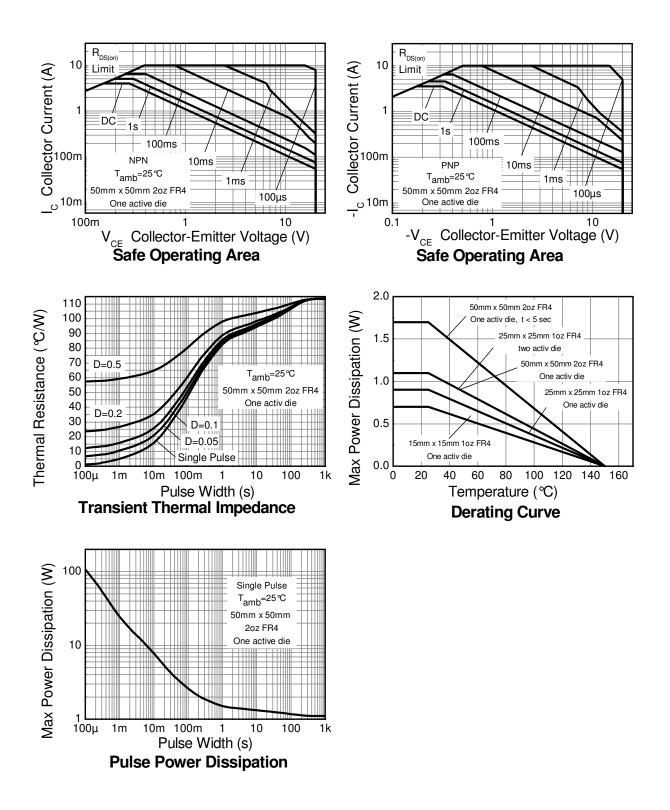
10. For device with two active dice running at equal power, split heatsink 50% to each collector.

11. Thermal resistance from junction to solder-point (at the end of the collector lead).

12. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





Electrical Characteristics – Q1 (NPN Transistor) (@T _A = +25 °C, unless otherwise specified.)						
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV CBO	100	140	—	V	$I_{C} = 100 \mu A, I_{E} = 0$
Collector-Emitter Breakdown Voltage (Note 13)	BV _{CEO}	20	35	—	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BVEBO	7	8.3	_	V	$I_{E} = 100 \mu A, I_{C} = 0$
Emitter-Collector breakdown voltage (base open)	BV _{ECO}	5	6	_	V	$I_{E} = 100 \mu A$
Collector Cutoff Current	I _{CBO}	_	<1	50 0.5	nA μA	V _{CB} = 100V V _{CB} = 100V, T _A = +100 ℃
Collector Cutoff Current	I _{EBO}		<1	50	nA	V _{EB} = 5.6V
ON CHARACTERISTICS (Note 13)						
DC Current Gain	h _{FE}	300 280 140 —	450 420 210 15	900 — — —	_	$\begin{split} I_{C} &= 10 \text{mA}, V_{CE} = 2 \text{V} \\ I_{C} &= 1 \text{A}, V_{CE} = 2 \text{V} \\ I_{C} &= 4 \text{A}, V_{CE} = 2 \text{V} \\ I_{C} &= 15 \text{A}, V_{CE} = 2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}		40 60 95 140	50 75 115 190	mV	$\begin{split} I_{C} &= 1.0A, \ I_{B} = 100 \text{mA} \\ I_{C} &= 1.0A, \ I_{B} = 20 \text{mA} \\ I_{C} &= 2.0A, \ I_{B} = 40 \text{mA} \\ I_{C} &= 4A, \ I_{B} = 200 \text{mA} \end{split}$
Base-Emitter Saturation Voltage	V _{BE(sat)}		940	1,050	mV	$I_{\rm C} = 4$ A, $I_{\rm B} = 200$ mA
Base-Emitter Turn-On Voltage	V _{BE(on)}	_	810	900	mV	$I_C = 4A, V_{CE} = 2V$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	Cobo		17	25	pF	$V_{CB} = 10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f _T		215		MHz	$V_{CE} = 10V, I_{C} = 50mA, f = 100MHz$
Delay Time	t _d		68		ns	
Rise Time	tr		72		ns	$V_{CC} = 10V, I_C = 1A, I_{B1} = -I_{B2} = 10mA$
Storage Time	ts		361		ns	$v_{CC} = 10v$, $i_C = 1A$, $i_{B1} = -i_{B2} = 1011A$
Fall Time	t _f		64		ns	

Notes: 13. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.

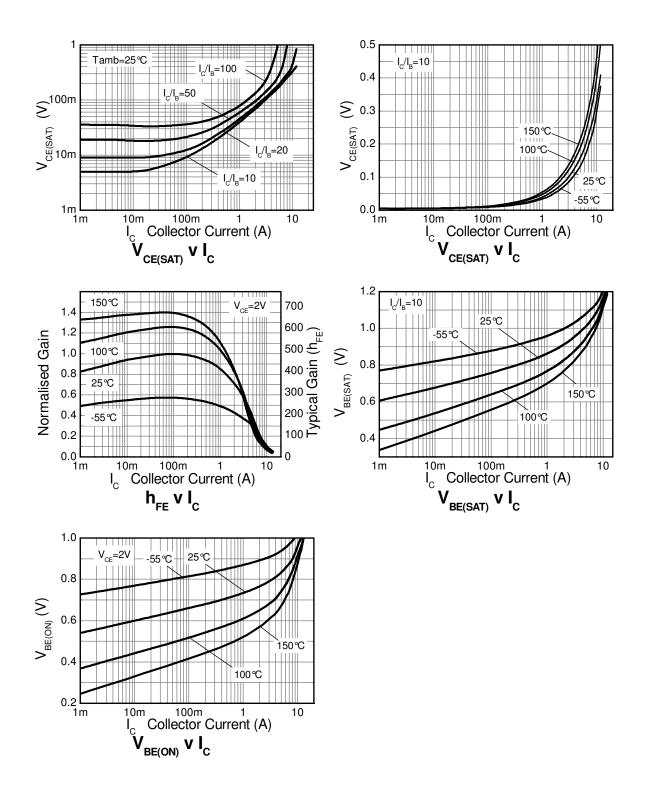


Electrical Characteristics – Q2 (PNP Transistor) (@T _A = +25 °C, unless otherwise specified.)						
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						·
Collector-Base Breakdown Voltage	BV _{CBO}	-25	-55	_	V	$I_{\rm C} = -100 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 13)	BV _{CEO}	-20	-45	_	V	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.3	_	V	$I_{E} = -100 \mu A, I_{C} = 0$
Collector Cutoff Current	I _{CBO}		< -1	-50 -0.5	nA μA	V _{CB} = -25V V _{CB} = -25V, T _A = +100 ℃
Collector Cutoff Current	I _{EBO}		< -1	-50	nA	V _{EB} = -5.6V
ON CHARACTERISTICS (Note 13)	•					·
DC Current Gain	hFE	300 170 65 —	450 300 100 15	900 — —		$\begin{split} I_C &= -10 mA, V_{CE} = -2 V \\ I_C &= -1.0 A, V_{CE} = -2 V \\ I_C &= -3.5 A, V_{CE} = -2 V \\ I_C &= -10 A, V_{CE} = -2 V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}	 	-55 -100 -185 -190	-65 -135 -280 -250	mV	$I_{C} = -1.0A, I_{B} = -100mA$ $I_{C} = -1.0A, I_{B} = -20mA$ $I_{C} = -2.0A, I_{B} = -40mA$ $I_{C} = -3.5A, I_{B} = -175mA$
Base-Emitter Saturation Voltage	V _{BE(sat)}	—	-925	-1,000	mV	$I_{C} = -3.5A, I_{B} = -175mA$
Base-Emitter Turn-On Voltage	V _{BE(on)}	—	-835	-900	mV	I _C = -3.5A, V _{CE} = -2V
SMALL SIGNAL CHARACTERISTICS			-	-	-	
Output Capacitance	Cobo		21	30	pF	V _{CB} = -10V, f = 1.0MHz
Current Gain-Bandwidth Product	f _T		290		MHz	$V_{CE} = -10V, I_{C} = -50mA, f = 100MHz$
Delay Time	t _d		56		ns	
Rise Time	tr		68	_	ns	$V_{CC} = -10V, I_{C} = -1A,$
Storage Time	ts		158		ns	$I_{B1} = -I_{B2} = -10mA$
Fall Time	tf		59		ns]

Note: 13. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.

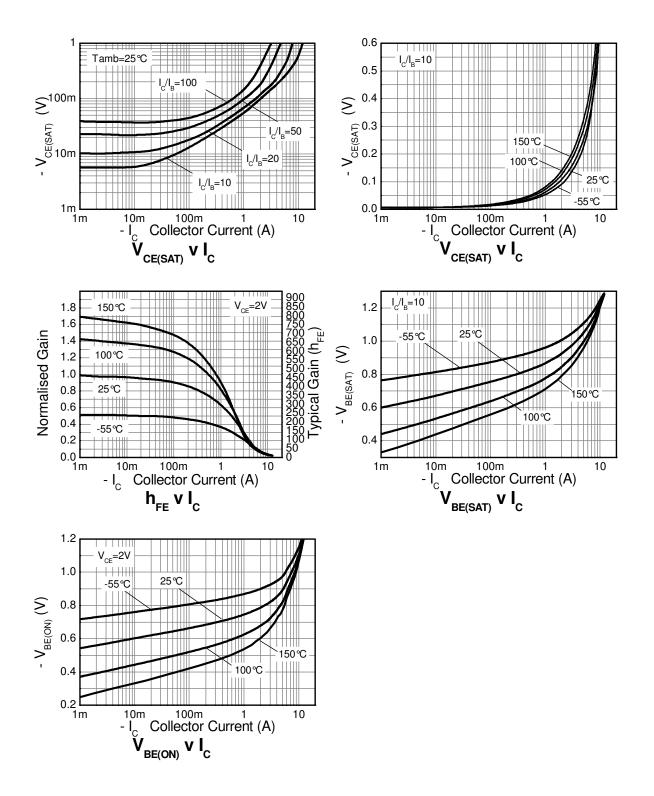


Typical Electrical Characteristics – Q1 (NPN Transistor) (@T_A = +25 °C, unless otherwise specified.)





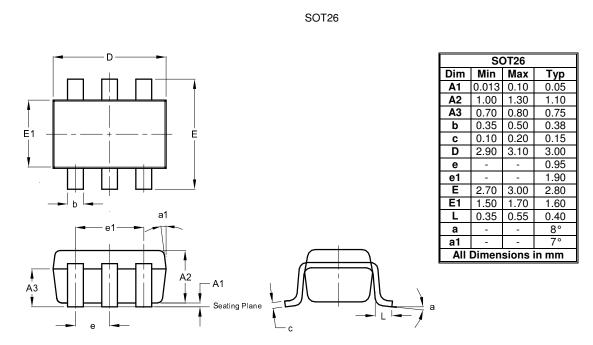
Typical Electrical Characteristics – Q2 (PNP Transistor) (@T_A = +25 °C, unless otherwise specified.)





Package Outline Dimensions

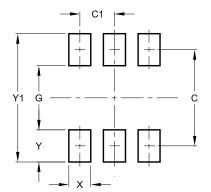
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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